Amendments to the Claims:

This listing of the claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A heating device within an integrated circuit, comprising:

a first conductive lead;

a second conductive lead;

a third conductive lead;

a first resistive region connected between the first conductive lead and the third conductive lead; and,

a second resistive region connected between the second conductive lead and the third conductive lead;

wherein a side formed by the first conductive lead and the first resistive region is parallel to a side formed by the second conductive lead and the second resistive region;

wherein an insulator is placed between the side formed by the first conductive lead and the first resistive region and the side formed by the second conductive lead and the second resistive region, except for at least one area directly between the first resistive region and the second resistive region, the at least one area including a third resistive region immediately adjacent to the third conductive lead, an entire first side of the third resistive region being in

physical and electrical contact with ~~both~~ the first resistive region and an entire second side of the third resistive region being in physical and electrical contact with the second resistive region.

2. (Canceled)

3. (Canceled)

4. (Previously presented) A heating device as in claim 1:

wherein resistivity of the third resistive region is approximately equal to resistivity of the first resistive region and of the second resistive region.

5. (Canceled)

6. (Withdrawn) A heating device as in claim 1:

wherein the at least one area includes a plurality of areas where third resistive regions separate the first resistive region and the second resistive region; and,

wherein resistivity of the third resistive regions is approximately equal to resistivity of the first resistive region and of the second resistive region.

7. (Withdrawn) A heating device as in claim 1:

wherein the at least one area includes a plurality of areas where third resistive regions separate the first resistive region and the second resistive region; and,

wherein resistivity of the third resistive regions is higher than resistivity of the first resistive region and of the second resistive region.

8. (Original) A heating device as in claim 1 wherein the integrated circuit is connected to a planar light circuit.

9. (Original) A heating device as in claim 1 wherein the integrated circuit is used within an inkjet printhead.

10 through 20. (Canceled)